

4V Drive Pch+SBD MOSFET

V _{DSS}	-45V
R _{DS(on)} (Max.)	800mΩ
I _D	±0.7A
P _D	1.0W

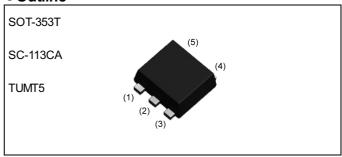
Features

- 1) The US5U35 combines Pch MOSFET with a Schottky barrier diode in a single
- 2) High-speed switching, Low On-resistance
- 3) Built-in Low V_F schottky barrier diode
- 4) Pb-free lead plating; RoHS compliant

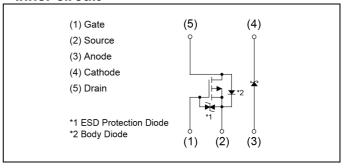
Application

switching

Outline



•Inner circuit



Packaging specifications

	Packing	Embossed Tape
	Reel size (mm)	180
Туре	Tape width (mm)	8
	Basic ordering unit (pcs)	3000
	Taping code	TR
	Marking	U35

● **Absolute maximum ratings** (T_a = 25°C ,unless otherwise specified)

<MOSFET>

Parameter	Symbol	Value	Unit
Drain - Source voltage	V_{DSS}	-45	V
Gate - Source voltage	V _{GSS}	±20	V
Continuous drain current	I _D	±0.7	Α
Pulsed drain current	I _{DP} *1	±2.8	Α
Continuous source current (body diode)	I _S	-0.4	Α
Pulsed source current (body diode)	I _{SP} *1	-2.8	Α
Power dissipation	P _D *3	0.7	W/element
Junction temperature	T _j	150	°C

● Absolute maximum ratings (T_a = 25°C)

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Parameter	Symbol	Value	Unit
Repetitive peak reverse voltage	V_{RM}	45	V
Reverse voltage	V _R	40	V
Forward current	I _F	100	mA
Forward current surge peak	I _{FSM} *2	1.0	Α
Power dissipation	P _D *3	0.5	W/element
Junction temperature	T _j	150	°C

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Parameter	Symbol	Value	Unit
Power dissipation	P _D *3	1.0	W/total
Operating junction and storage temperature range	T _{stg}	-55 to +150	°C

●Electrical characteristics (T_a = 25°C)

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Daramatar	Cymah ol	Conditions	Values			Linit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Unit
Gate - Source leakage current	I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	±10	μΑ
Drain - Source breakdown voltage	V _{(BR)DSS}	$V_{GS} = 0V$, $I_D = -1mA$	-45	-	-	٧
Zero gate voltage drain current	I _{DSS}	V _{DS} = -45V, V _{GS} = 0V	-	-	-1	μA
Gate threshold voltage	V _{GS(th)}	$V_{DS} = -10V, I_{D} = -1mA$	-1.0	-	-2.5	V
		$V_{GS} = -10V, I_D = -0.7A$	-	600	800	
Static drain - source on - state resistance	R _{DS(on)} *4	$V_{GS} = -4.5V, I_D = -0.7A$	-	900	1300	mΩ
		$V_{GS} = -4.0V, I_D = -0.35A$	-	1000	1400	
Forward Transfer Admittance	Y _{fs} *4	V _{DS} = -10V, I _D = -0.7A	0.6	-	-	S



●Electrical characteristics (T_a = 25°C)

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Parameter	Symbol	Conditions	Values			Unit
Parameter	Symbol	Conditions	Min.	Тур.	Max.	Offit
Input capacitance	C _{iss}	V _{GS} = 0V	-	120	-	
Output capacitance	C _{oss}	V _{DS} = -10V	-	14	-	pF
Reverse transfer capacitance	C _{rss}	f = 1MHz	-	11	-	
Turn - on delay time	t _{d(on)} *4	$V_{DD} \simeq$ -25V, V_{GS} = -10V	-	6	-	
Rise time	t _r *4	I _D = -0.35A	-	5	-	no
Turn - off delay time	t _{d(off)} *4	R _L = 71Ω	-	17	-	ns
Fall time	t _f *4	$R_G = 10\Omega$	-	6	-	

• Gate charge characteristics $(T_a = 25^{\circ}C)$

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Parameter	Symbol	Conditions	Values			Lloit
		Conditions	Min.	Тур.	Max.	Unit
Total gate charge	Qg*4		-	1.7	-	
Gate - Source charge	Q _{gs} *4	$V_{DD} \simeq -25V, I_{D} = -0.7A$ $V_{GS} = -5V$	-	0.8	-	nC
Gate - Drain charge	Q _{gd} *4	763 07	-	0.5	-	

● Body diode electrical characteristics (Source-Drain) (T_a = 25°C)

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Parameter	Symbol	Conditions	Values			l leit
		Conditions	Min.	Тур.	Max.	Unit
Forward voltage	V_{SD}^{*4}	$V_{GS} = 0V, I_{S} = -0.7A$	-	-	-1.2	V

● Electrical characteristics (T_a = 25°C)

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Parameter	Symbol	Conditions	Values			l lmit
		Conditions	Min.	Тур.	Max.	Unit
Forward voltage	V_{F}	I _F = 100mA	-	-	0.55	V
Reverse current	I _R	V _R = 10V	-	-	30	μA

^{*1} Pw \leq 10 μ s, Duty cycle \leq 1%

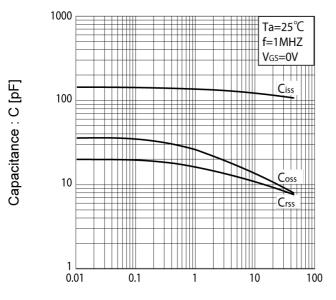
^{*2 60}Hz-1 cycle

^{*3} Mounted on a ceramic boad (30×30×0.8mm)

^{*4} Pulsed

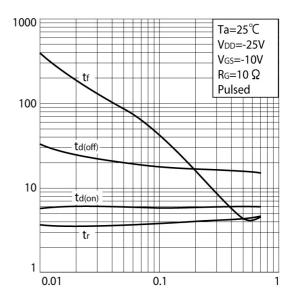
• Electrical characteristic curves < MOSFET>

Fig.1 Typical Capacitance vs. Drain - Source Voltage



Drain - Source Voltage : -V_{DS} [V]

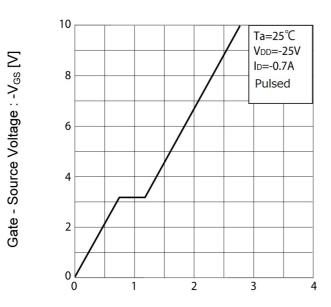
Fig.2 Switching Characteristics



Switching Time : t [ns]

Drain Current: -ID [A]

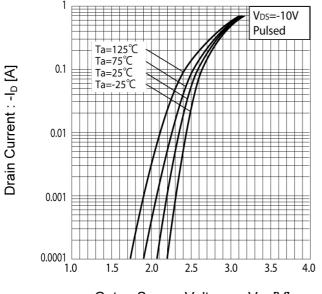
Fig.3 Dynamic Input Characteristics



Total Gate Charge : Q_g [nC]

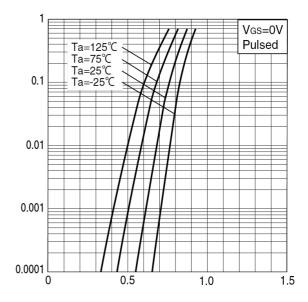
● Electrical characteristic curves < MOSFET>

Fig.4 Typical Transfer Characteristics



Gate - Source Voltage : -VGS [V]

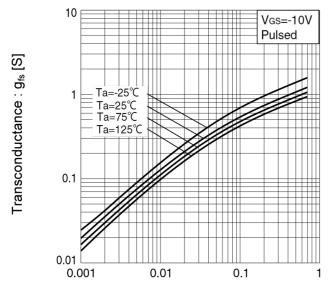
Fig.5 Source Current vs. Source Drain Voltage



Source Current : -I_S [A]

Source - Drain Voltage : -V_{SD} [V]

Fig.6 Transconductance vs. Drain Current



Drain Current : -I_D [A]

• Electrical characteristic curves < MOSFET>

Fig.7 Static Drain - Source On - State Resistance vs. Drain Current (I)

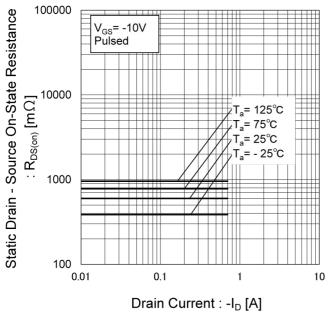
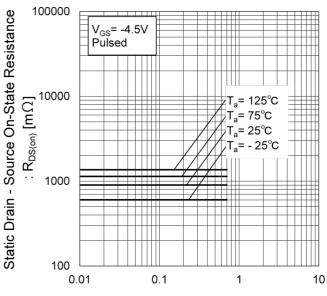
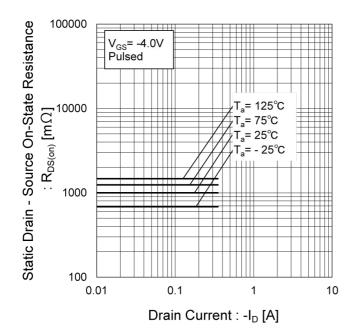


Fig.8 Static Drain - Source On - State Resistance vs. Drain Current (II)



Drain Current: -ID [A]

Fig.9 Static Drain - Source On - State Resistance vs. Drain Current (III)



● Electrical characteristic curves < Diode >

Fig.11 Forward Current vs. Forward Voltage

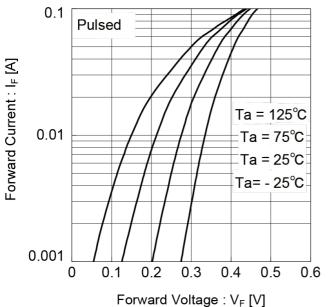
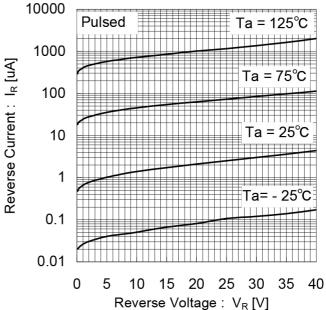


Fig.12 Reverse Current vs. Reverse Voltage



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Measurement circuits

Fig.1-1 Switching Time Measurement Circuit

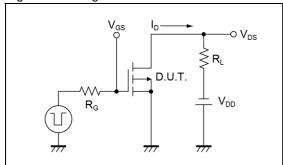


Fig.2-1 Gate Charge Measurement Circuit

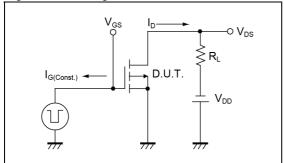


Fig.1-2 Switching Waveforms

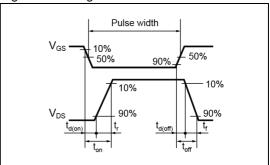
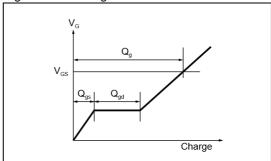


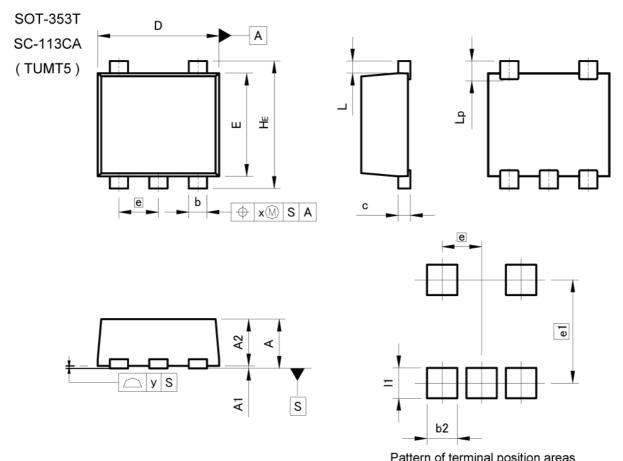
Fig.2-2 Gate Charge Waveform



Notice

- SBD has a large reverse leak current compared to other type of diode. Therefore, it would raise a junction temperature, and increase a reverse power loss. Further rise of inside temperature would cause a thermal runaway. This built-in SBD has low V_F characteristics and therefore, higher leak current. Please consider enough the surrounding temperature, generating heat of MOSFET and the reverse current.
- 2. This product might cause chip aging and breakdown under the large electrified environment. Please consider to design ESD protection circuit.

Dimensions



Pattern of terminal position areas [Not a pattern of soldering pads]

DIM	MILIM	ETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α	-	0.85	-	0.033
A1	0.00	0.10	0.000	0.004
A2	0.72	0.82	0.028	0.032
b	0.25	0.40	0.010	0.016
С	0.12	0.22	0.005	0.009
D	1.90	2.10	0.075	0.083
E	1.60	1.80	0.063	0.071
е	0.65		0.026	
HE	2.00	2.20	0.079	0.087
L	0.5	20	0.0	08
Lp		0.40	1	0.016
х	_	0.10	-	0.004
У	-	0.10	i=	0.004

DIM	DIM MILIMETERS			HES
MIN		MAX	MIN	MAX
b2	-	0.50]	0.020
e1	1.70		0.0	67
11	-	0.50	-	0.020

Dimension in mm/inches

Notice

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(Note1) Medical Equipment Classification of the Specific Applications

JAPAN	USA	EU	CHINA
CLASSⅢ	CLASSII	CLASS II b	CLASSIII
CLASSIV		CLASSⅢ	

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 - [b] Use of our Products outdoors or in places where the Products are exposed to direct sunlight or dust
 - [c] Use of our Products in places where the Products are exposed to sea wind or corrosive gases, including Cl₂, H₂S, NH₃, SO₂, and NO₂
 - [d] Use of our Products in places where the Products are exposed to static electricity or electromagnetic waves
 - [e] Use of our Products in proximity to heat-producing components, plastic cords, or other flammable items
 - [f] Sealing or coating our Products with resin or other coating materials
 - [g] Use of our Products without cleaning residue of flux (even if you use no-clean type fluxes, cleaning residue of flux is recommended); or Washing our Products by using water or water-soluble cleaning agents for cleaning residue after soldering
 - [h] Use of the Products in places subject to dew condensation
- 4. The Products are not subject to radiation-proof design.
- 5. Please verify and confirm characteristics of the final or mounted products in using the Products.
- 6. In particular, if a transient load (a large amount of load applied in a short period of time, such as pulse. is applied, confirmation of performance characteristics after on-board mounting is strongly recommended. Avoid applying power exceeding normal rated power; exceeding the power rating under steady-state loading condition may negatively affect product performance and reliability.
- 7. De-rate Power Dissipation depending on ambient temperature. When used in sealed area, confirm that it is the use in the range that does not exceed the maximum junction temperature.
- 8. Confirm that operation temperature is within the specified range described in the product specification.
- ROHM shall not be in any way responsible or liable for failure induced under deviant condition from what is defined in this document.

Precaution for Mounting / Circuit board design

- 1. When a highly active halogenous (chlorine, bromine, etc.) flux is used, the residue of flux may negatively affect product performance and reliability.
- 2. In principle, the reflow soldering method must be used on a surface-mount products, the flow soldering method must be used on a through hole mount products. If the flow soldering method is preferred on a surface-mount products, please consult with the ROHM representative in advance.

For details, please refer to ROHM Mounting specification

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- 1. If change is made to the constant of an external circuit, please allow a sufficient margin considering variations of the characteristics of the Products and external components, including transient characteristics, as well as static characteristics.
- You agree that application notes, reference designs, and associated data and information contained in this document are presented only as guidance for Products use. Therefore, in case you use such information, you are solely responsible for it and you must exercise your own independent verification and judgment in the use of such information contained in this document. ROHM shall not be in any way responsible or liable for any damages, expenses or losses incurred by you or third parties arising from the use of such information.

Precaution for Electrostatic

This Product is electrostatic sensitive product, which may be damaged due to electrostatic discharge. Please take proper caution in your manufacturing process and storage so that voltage exceeding the Products maximum rating will not be applied to Products. Please take special care under dry condition (e.g. Grounding of human body / equipment / solder iron, isolation from charged objects, setting of lonizer, friction prevention and temperature / humidity control).

Precaution for Storage / Transportation

- 1. Product performance and soldered connections may deteriorate if the Products are stored in the places where:
 - [a] the Products are exposed to sea winds or corrosive gases, including Cl2, H2S, NH3, SO2, and NO2
 - [b] the temperature or humidity exceeds those recommended by ROHM
 - [c] the Products are exposed to direct sunshine or condensation
 - [d] the Products are exposed to high Electrostatic
- Even under ROHM recommended storage condition, solderability of products out of recommended storage time period
 may be degraded. It is strongly recommended to confirm solderability before using Products of which storage time is
 exceeding the recommended storage time period.
- 3. Store / transport cartons in the correct direction, which is indicated on a carton with a symbol. Otherwise bent leads may occur due to excessive stress applied when dropping of a carton.
- 4. Use Products within the specified time after opening a humidity barrier bag. Baking is required before using Products of which storage time is exceeding the recommended storage time period.

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